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(21) International Application Number: PCT/US95/13654 (22) International Filing Date: 19 October 1995 (19.10.95) (30) Priority Data: 94203040.4 20 October 1994 (20.10.94) EP (34) Countries for which the regional or international application was filed: AT et al. (71) Applicant (for all designated States except US): THE PROCTER & GAMBLE COMPANY [US/US]; One Procter & Gamble Plaza, Cincinnati, OH 45202 (US). (72) Inventors; and (75) Inventors/Applicants (for US only): GEILICH, Ralf [DE/DE]; Im Schanzbuck 16, D-74564 Crailsheim (DE). PLUMLEY, Julian , Ashton [GB/DE]; Neuwiesenweg 1, D-74589 Satteldorf (DE). (74) Agents: REED, T., David et al.; The Procter & Gamble Company, 5299 Spring Grove Avenue, Cincinnati, OH 45217 (US).		(81) Designated States: AM, AU, BB, BG, BR, BY, CA, CN, CZ, EE, FI, GE, HU, IS, JP, KE, KG, KP, KR, KZ, LK, LR, LT, LV, MD, MG, MK, MN, MX, NO, NZ, PL, RO, RU, <u>SG</u> , SI, SK, TJ, TT, UA, US, UZ, VN, OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG), ARIPO patent (KE, MW, SD, SZ, UG). Published With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.
(54) Title: PROCESS TO PROVIDE MATERIAL CONNECTIONS FOR ABSORBENT ARTICLES BY SOLDERING		
(57) Abstract The present invention relates to a process for providing connections of the materials making up disposable absorbent articles. In particular baby diapers, incontinence products and sanitary napkins which are fabricated in continuous processes are beneficially held together by soldering the materials where connections of them are desired. Replacing the currently used technique of adhesively attaching materials by soldering materials has the benefit of having non sticky surfaces once the solder is cooled to a temperature below its solidifying temperature. This is highly desirable where the otherwise sticky surface comes into contact with the skin of users of disposable absorbent articles or could cause adhesive build up on machine parts during the manufacturing of such articles.		